

January 18th – 21st 2000, Beijing, China

Source: RAN WG1
To: RAN WG2, RAN WG3, RAN WG4
Title: Time schedule on the work on the Low Chip Rate TDD in RAN WG1

RAN WG1 would like to inform RAN WG2, WG3 and WG4 on their intended time plan for the work item on the low chip rate TDD option. The provisional time plan in RAN WG1 on the work item is as follows:

- From 1/2000 to 5/2000, WG1 intends to create a technical report on the low chip rate TDD physical layer. This report shall be submitted to TSG RAN #8 in June 2000 for approval.
- Based on the report it should be decided at TSG RAN #8 in 6/2000 which new specifications are possibly required and what will be accommodated in the existing specifications.
- By 9/2000 (TSG RAN#9), WG1 would present possible new specifications (if required to be produced) and Change Requests to existing TDD specs on the 1.28 Mchips/s TDD details for TSG RAN approval.
- By 12/2000, possible remaining corrections and clarifications of the low chip rate TDD issues shall be finalised.

The work plan will be discussed in the TSG RAN #7, but WG1 sees interdependencies in the work to be carried out in the different working groups and, therefore, would also like to get feedback from other WG's on the schedule before preparing the proposal for the time plan for the TSG RAN.